XILINXPWR-083 (HPA-083)

SWIFTTM (TPS54xxx series) DC/DC Converter-based Power Management Solution Providing I_{CCINT} =1.5A from V_{IN} =5V

SUPPORTS:

SpartanTM-3

FEATURES:

- High efficiency minimizes heat
- Interchange SWIFTTM device to support 1.5 A to 3 A load currents
 - o 1.5A (TPS54110) and 3A (TPS54310) synchronous SWIFT devices are pin-pin compatible
- Use of the TPS54x10 adjustable devices allow
 - o use of smallest inductor and/or specific type of output capacitor
 - o flexibility to re-compensate as needed, depending on the bypass/decoupling capacitors used with the FPGA
- In-rush current (for charging decoupling caps and FPGA start-up) that places a demand on the input power supply is minimized by the use of optional
 - o Integrated soft-start configured with an capacitor to provide 10 ms rise time for $V_{\rm CCINT}$ and $V_{\rm CCO}$
 - o Sequencing of V_{CCINT}, V_{CCAUX}, then V_{CCO} using PWRGD and ENABLE
- High UVLO trip point and integrated soft-start of the SWIFTTM devices eliminates the need for an external Supply Voltage Supervisor (SVS) to monitor the input rail.
- Additional V_{CCO} rails easily added and sequenced (if desired) using the TPS54xxx PWRGD and ENABLE.
- The design meets Xilinx's V_{CCINT} and V_{CCO} start-up profile requirements, where applicable, including monotonic voltage ramp, in-rush current and power voltage ramp time requirements.

IMPORTANT WEB LINKS:

- Link to the TI home page for Xilinx FPGA power management solutions at http://www.ti.com/xilinxfpga for more information and other reference designs.
- Link to datasheets at http://focus.ti.com/lit/ds/symlink/TPS54110.pdf.
- Link to SWIFTTM design software tool at http://focus.ti.com/docs/toolsw/folders/print/swift-sw.html to assist further optimization/customization of design.

IMPLEMENTATION NOTES:

- **Sequencing:** Although Xilinx FPGAs **do NOT require it**, this reference design employs sequencing. This practice is consistent with good power supply design and prevents the input power supply from being pulled down due to supporting in-rush currents for charging large capacitive loads.

- Additional Capacitance:

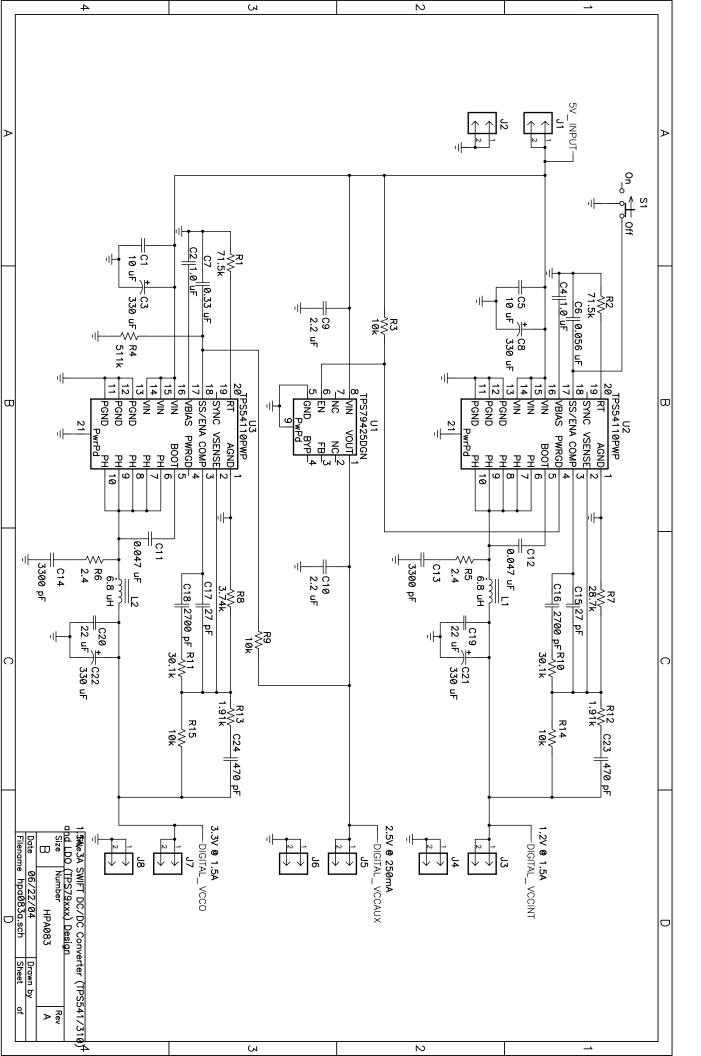
- o The TPS54110's have been compensated to allow for up to the following additional capacitance on each rail:
 - 12 uF in ceramics in parallel with
 - two 330 uF capacitors, each with ESR between 0.1 and 2 ohms. If more bypass capacitance or bulk capacitors with ESR outside the range above is used, each TPS54x10 control loop may need to be re-

above is used, each TPS54x10 control loop may need to be recompensated using the SWIFT design software.

- V_{CCAUX}: V_{CCAUX} powers time-critical resources in the FPGA, including the Digital Clock Managers (DCMs). Therefore, this supply voltage is especially susceptible to power supply noise. V_{CCAUX} can share a power plane with V_{CCO}, but only if V_{CCO} does not have excessive noise. Changes in V_{CCAUX} voltage beyond 200 mV peak-to-peak should take place no faster than 10 mV per millisecond.
- Modifications:
 - o Adapt for $V_{IN} = 3.3 \text{ V}$ by omitting U3.

QUESTIONS?

- Send an email to **fpgasupport@list.ti.com**



| | e: HPA083A_bom.x | s | | | | |
|----------|--|--|-----------|-----------|--------------------|--|
| Date: 06 | 6/22/2004 | | | | | |
| | | HPA083A BOM | | | | |
| COUNT | RefDes | DESCRIPTION | SIZE | MFR | PART NUMBER | |
| 2 | C1, C5 | Capacitor, Ceramic, 10-uF, 6.3-V, X5R, 10% | 805 | muRata | GRM21BR60J106KE01 | |
| 2 | C11, C12 | Capacitor, Ceramic, 0.047-uF, 25-V, X7R, 10% | 603 | muRata | GRM188R71E473KA01 | |
| 2 | C13, C14 | Capacitor, Ceramic, 3300-pF, 50-V, X7R, 10% | 603 | muRata | GRM188R71H332KA01 | |
| 2 | C15, C17 | Capacitor, Ceramic, 27-pF, 50-V, C0G, 5% | 603 | muRata | GRM1885C1H270JA01D | |
| 2 | C16, C18 | Capacitor, Ceramic, 2700-pF, 50-V, X7R, 10% | 603 | muRata | GRM188R71H272KA01D | |
| 2 | C19, C20 | Capacitor, Ceramic, 22-uF, 10-V, X5R, 10% | 1210 | muRata | GRM32ER61A226KA65 | |
| 2 | C2, C4 | Capacitor, Ceramic, 1.0-uF, 6.3-V, X5R, 10% | 603 | muRata | GRM188R60J105KA01 | |
| 2 | C23, C24 | Capacitor, Ceramic, 470-pF, 50-V, X7R, 10% | 603 | muRata | GRM188R71H471KA01 | |
| 4 | C3, C8, C21, C22 | Capacitor, Tantalum, 330-uF, 6.3-V, 600-milliohm, 20% | 7343(D) | Vishay | 293D337X96R3D2 | |
| 1 | C6 | Capacitor, Ceramic, 0.056-uF, 16-V, X7R, 10% | 603 | muRata | GRM188R71C563KC01 | |
| 1 | C7 | Capacitor, Ceramic, 0.33-uF, 10-V, X5R, 10% | 603 | muRata | GRM188R61A334KA61 | |
| 2 | C9, C10 | Capacitor, Ceramic, 2.2-uF, 6.3-V, X5R, 10% | 805 | muRata | GRM21BR60J225KC01 | |
| 8 | J1 - J8 | Header, 2-pin, 100mil spacing, (36-pin strip) | 0.100 x 2 | Sullins | PTC36SAAN | |
| 2 | L1, L2 | Inductor, SMT, 6.8-uH, 2.2-A, 75-milliohm | 0.51x0.37 | Coilcraft | DS3316P-682 | |
| 3 | R1, R2, R9 | Resistor, Chip, 71.5k-Ohms, 1/16-W, 1% | 603 | Std | Std | |
| 2 | R10, R11 | Resistor, Chip, 30.1k-Ohms, 1/16-W, 1% | 603 | Std | Std | |
| 2 | R12, R13 | Resistor, Chip, 1.91k-Ohms, 1/16-W, 1% | 603 | Std | Std | |
| 3 | R3, R14, R15 | Resistor, Chip, 10k-Ohms, 1/16-W, 1% | 603 | Std | Std | |
| 1 | R4 | Resistor, Chip, 511k-Ohms, 1/16-W, 1% | 603 | Std | Std | |
| 2 | R5, R6 | Resistor, Chip, 2.4-Ohms, 1/8-W, 1% | 1206 | Std | Std | |
| 1 | R7 | Resistor, Chip, 28.7k-Ohms, 1/16-W, 1% | 603 | Std | Std | |
| 1 | R8 | Resistor, Chip, 3.74k-Ohms, 1/16-W, 1% | 603 | Std | Std | |
| 1 | S1 | Switch, 1P2T, Slide, PC-mount, 200-mA | 79900 | E_Switch | EG1218 | |
| | | IC, Utralow-Noise, High PSRR, Fast RF 250 mA, LDO | | | | |
| 1 | U1 | Linear Regulators, 2.5-V | MSOP-8 | TI | TPS79425DGN | |
| 2 | U2, U3 | IC, SWIFT Power Controller, Adj-V, 1.5A | PWP20 | TI | TPS54110PWP | |
| 1 | | PCB, 3.1 ln x 2.4 ln x .062 ln | | Any | HPA083 | |
| Notes: | | es are ESD sensitive, ESD precautions shall be observed. | | | | |
| | These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable. | | | | | |
| | | | | | | |
| | 3. These assemblies must comply with workmanship standards IPC-A-610 Class 2. | | | | | |
| | 4. Ref designators marked with an asterisk ('**') cannot be substituted. | | | | | |
| | All other compor | nents can be substituted with equivalent MFG's components. | | | | |

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